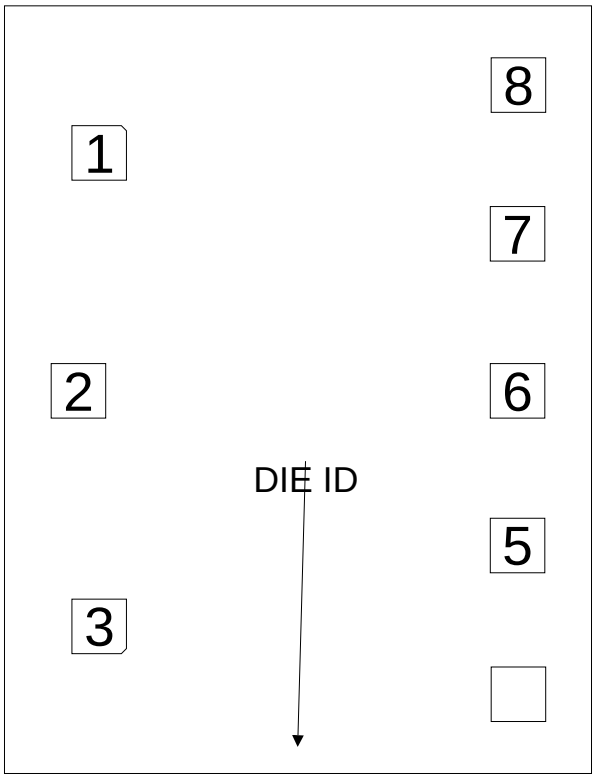
LM158A MD8 MW8
LOW POWER DUAL OPERATIONAL AMPLIFIER

JUN 20, 2008

DIE LAYOUT (E-STEP)



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM158E	Bond Pad Opening Size (min)	92.00µm x 92.00µm
Die Step	E	Bond Pad Metalization	AL 0.5%CU
Physical Attributes		Passivation	PECVDOX NITRIDE
Wafer Diameter	150mm	Back Side Metal	Bare Back
Die Size (Drawn)	990.60µm x 1295.40µm 39.0mils x 51.0mils	Back Side Connection	Floating
Thickness	304.8µm Nominal		
Min Pitch	261µm		
Note: All values are rounded to the nearest micron.			
Special Assembly Requirements:			

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Die Bond Pad Coordinate Locations(E-Step)
(Referenced to die center, coordinates in µm) NC = No Connection, N.U. = Not Used

Signal Name	Pad Number	X/Y Coordinates		Pad Size		
		X	Y	X		Y
OUTPUT B	1	-335	399	92	x	92
V +	2	-370	-2	92	x	92
OUTPUT A	3	-335	-399	92	x	92
INPUT A -	4	372	-514	92	x	92
INPUT A +	5	370	-263	92	x	92
GND	6	370	-2	92	x	92
INPUT B +	7	370	263	92	x	92
INPUT B -	8	372	514	92	x	92

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Notes

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